

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
I_{PP}	Peak Current ($t_p=8/20\mu s$)	4	A
T_{OP}	Operating Temperature	-40 to 125	°C
T_{STOR}	Storage Temperature	-55 to 150	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Thermal Information

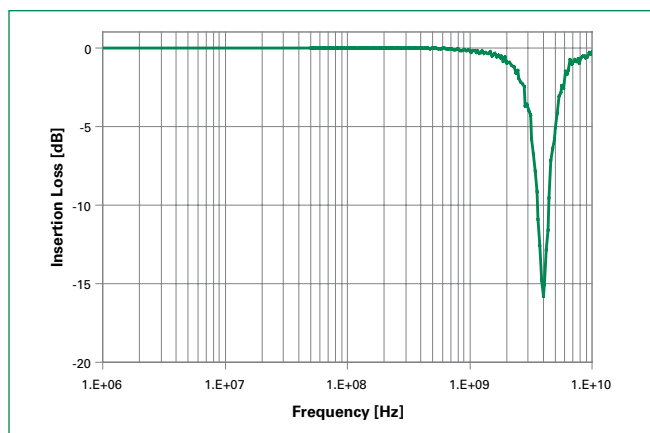
Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

Electrical Characteristics ($T_{OP}=25^{\circ}C$)

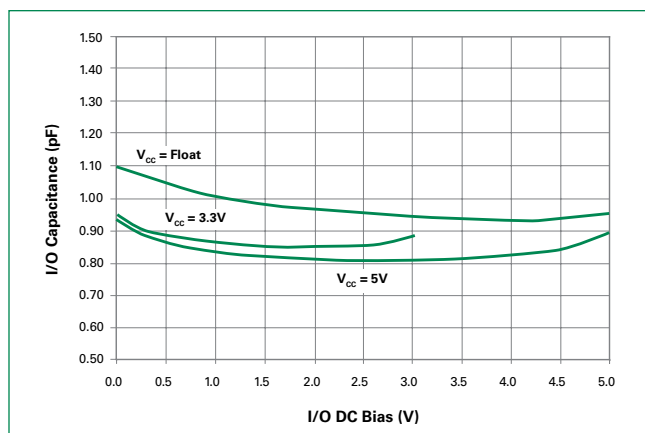
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V_{RWM}	$I_R \leq 1\mu A$			6	V
Reverse Leakage Current ¹	I_{LEAK}	$V_R=3.3V$			10	nA
Clamp Voltage ¹	V_C	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		10.0	12.0	V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		11.8	15.0	V
ESD Withstand Voltage ¹	V_{ESD}	IEC 61000-4-2 (Contact)	± 12			kV
		IEC 61000-4-2 (Air)	± 15			kV
Dynamic Resistance	R_{DYN}	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.8		Ω
Diode Capacitance ¹	$C_{I/O-GND}$	Reverse Bias=0V	0.95	1.1	1.25	pF
		Reverse Bias=1.65V	0.7	0.85	1	pF
Diode Capacitance ¹	$C_{I/O-I/O}$	Reverse Bias=0V		0.5		pF

Note: ¹ Parameter is guaranteed by design and/or device characterization.

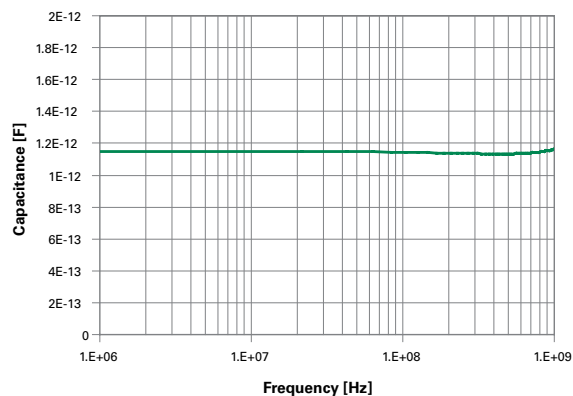
Insertion Loss (S21) I/O to GND



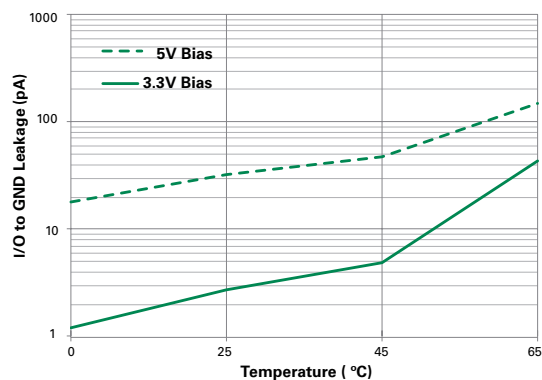
Capacitance vs. Bias Voltage



Capacitance vs. Frequency

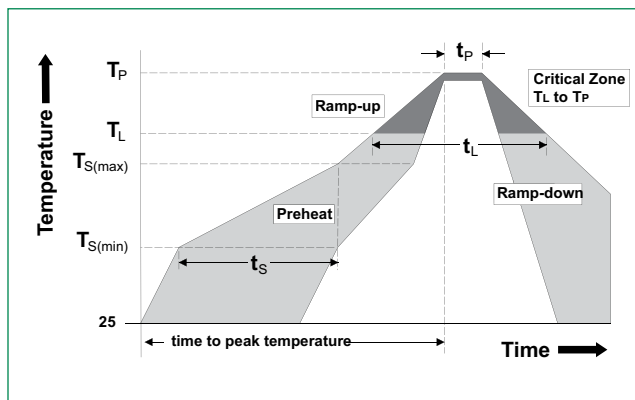


Leakage Current vs Temperature



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



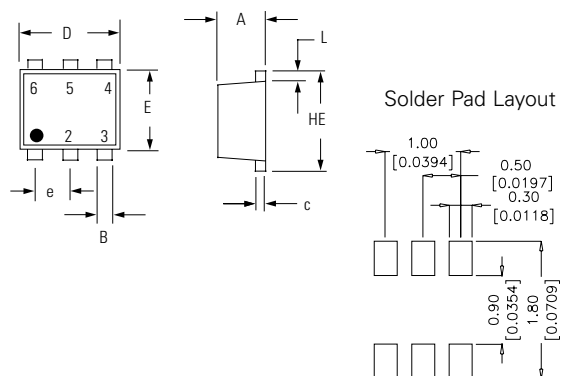
Product Characteristics

Lead Plating	Pre-Plated Frame
Lead Material	Copper Alloy
Lead Coplanarity	0.0004 inches (0.102mm)
Substitute Material	Silicon
Body Material	Molded Epoxy
Flammability	UL 94 V-0

Notes :

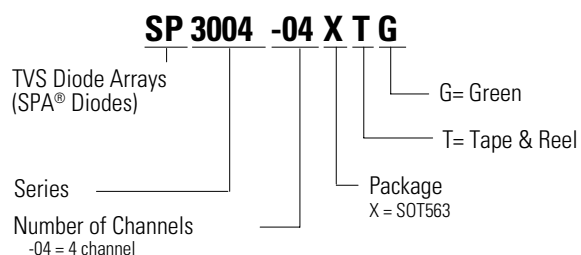
1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

Package Dimensions — SOT563

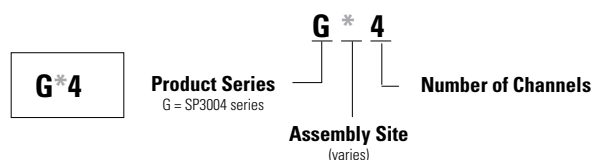


Package	SOT 563			
Pins	6			
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.50	0.60	0.020	0.024
B	0.17	0.27	0.007	0.011
c	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
e	0.50 BSC		0.020 BSC	
L	0.10	0.30	0.004	0.012
HE	1.50	1.70	0.059	0.067

Part Numbering System



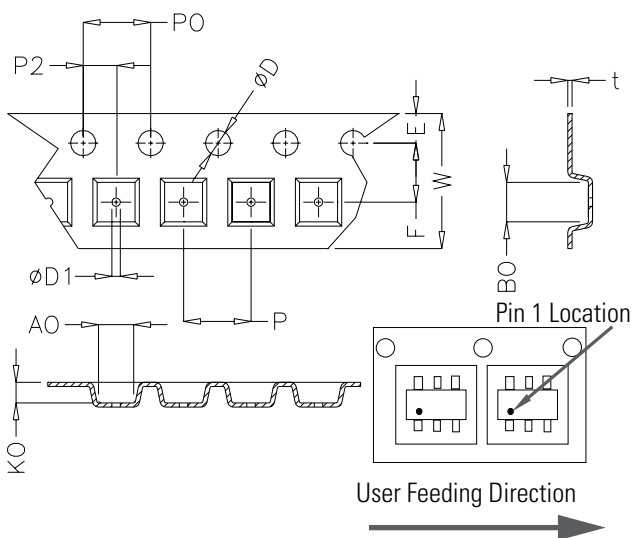
Part Marking System



Ordering Information

Part Number	Package	Marking	Min. Order Qty.
SP3004-04XTG	SOT563	G*4	3000

Embossed Carrier Tape & Reel Specification — SOT563



Symbol	Millimetres		Inches	
	Min	Max	Min	Max
E	1.65	1.85	0.065	0.073
F	3.45	3.55	0.135	0.139
P2	1.95	2.05	0.077	0.081
D	1.40	1.60	0.055	0.063
D1	0.45	0.55	0.017	0.021
P0	3.90	4.10	0.154	0.161
10P0	40.0± 0.20		1.574±0.008	
W	7.70	8.10	0.303	0.318
P	3.90	4.10	0.153	0.161
A0	1.73	1.83	0.068	0.072
B0	1.73	1.83	0.068	0.072
K0	0.64	0.74	0.025	0.029
t	0.22 max		0.009 max	

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Revised: 09/06/19